

# 74HC4060; 74HCT4060

## 14-stage binary ripple counter with oscillator

Rev. 4 — 10 February 2016

Product data sheet

### 1. General description

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The 74HC4060; 74HCT4060 is a 14-stage ripple-carry counter/divider and oscillator with three oscillator terminals (RS, RTC and CTC), ten buffered parallel outputs (Q3 to Q9 and Q11 to Q13) and an overriding asynchronous master reset (MR). The oscillator configuration allows design of either RC or crystal oscillator circuits. The oscillator may be replaced by an external clock signal at input RS. In this case, keep the oscillator pins (RTC and CTC) floating. The counter advances on the HIGH-to-LOW transition of RS. A HIGH level on MR clears all counter stages and forces all outputs LOW, independent of the other input conditions. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of  $V_{CC}$ .

### 2. Features and benefits

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- All active components on chip
- RC or crystal oscillator configuration
- Complies with JEDEC standard no. 7 A
- Input levels:
  - ◆ For 74HC4060: CMOS level
  - ◆ For 74HCT4060: TTL level
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$

### 3. Applications

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- Control counters
- Timers
- Frequency dividers
- Time-delay circuits



## 4. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC4060D	-40 °C to +125 °C	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74HCT4060D				
74HC4060DB	-40 °C to +125 °C	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74HCT4060DB				
74HC4060PW	-40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
74HC4060BQ	-40 °C to +125 °C	DHVQFN16	plastic dual in-line compatible thermal-enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 × 3.5 × 0.85 mm	SOT763-1
74HCT4060BQ				

## 5. Functional diagram

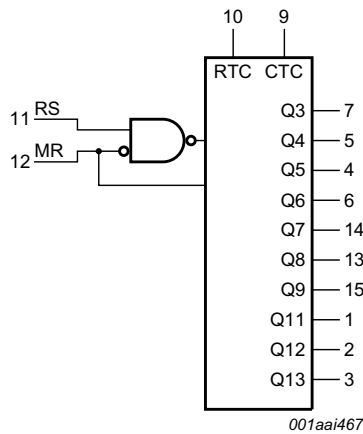


Fig 1. Logic symbol

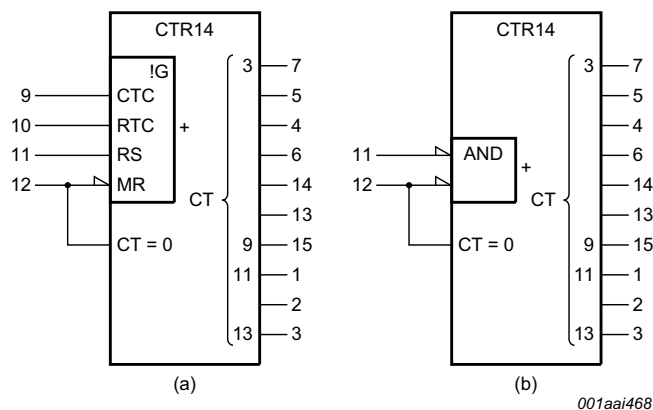
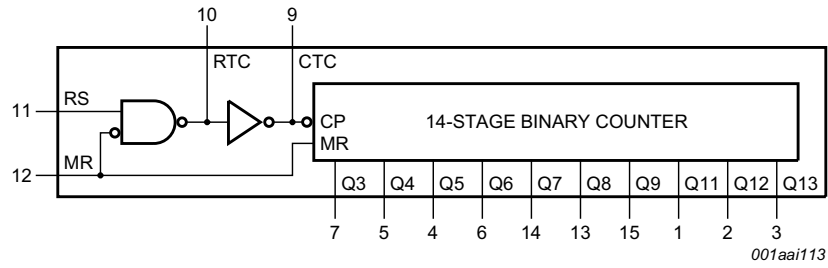
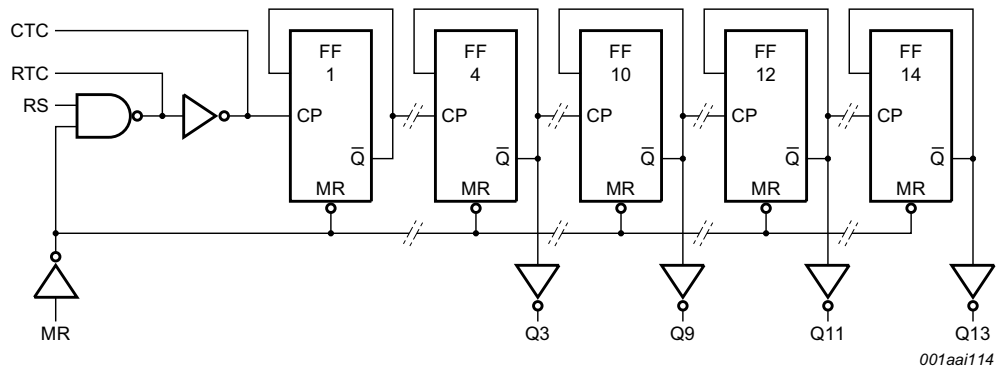


Fig 2. IEC logic symbol



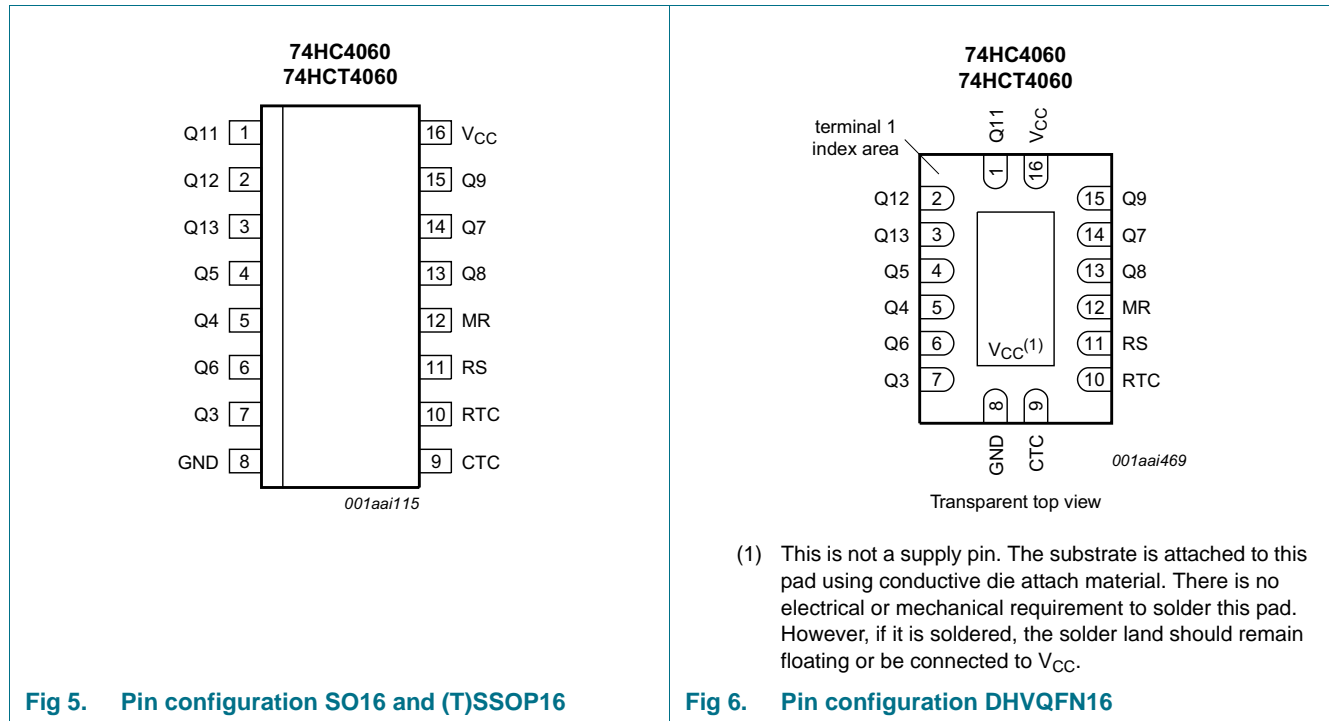
**Fig 3. Functional diagram**



**Fig 4. Logic diagram**

## 6. Pinning information

### 6.1 Pinning



### 6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
Q11 to Q13	1, 2, 3	counter output
Q3 to Q9	7, 5, 4, 6, 14, 13, 15	counter output
GND	8	ground (0 V)
CTC	9	external capacitor connection
RTC	10	external resistor connection
RS	11	clock input /oscillator pin
MR	12	master reset input (active HIGH)
V <sub>CC</sub>	16	supply voltage

## 7. Functional description

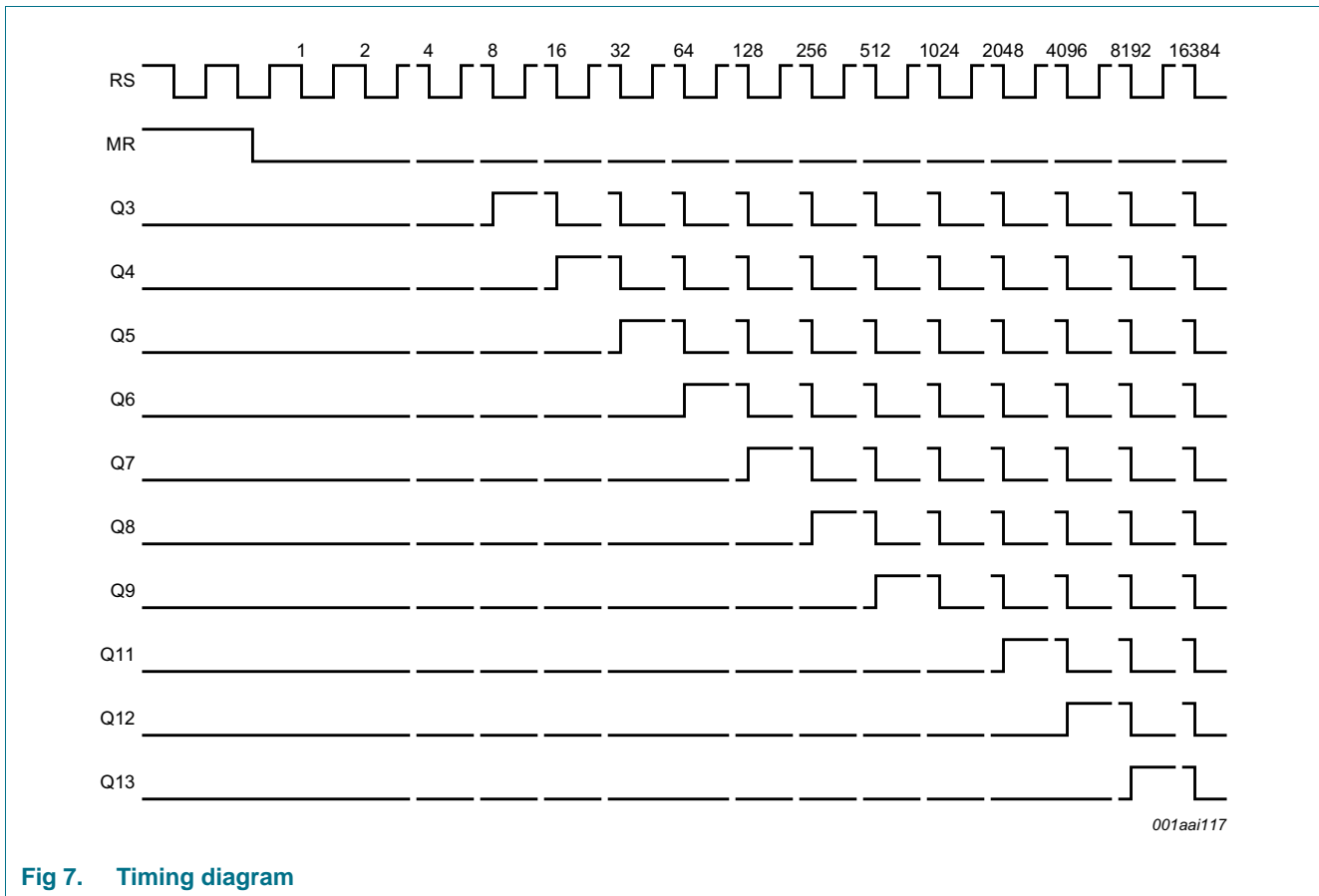


Fig 7. Timing diagram

## 8. Limiting values

Table 3. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+7	V
$I_{IK}$	input clamping current	$V_I < -0.5\text{ V}$ or $V_I > V_{CC} + 0.5\text{ V}$ [1]	-	$\pm 20$	mA
$I_{OK}$	output clamping current	$V_O < -0.5\text{ V}$ or $V_O > V_{CC} + 0.5\text{ V}$ [1]	-	$\pm 20$	mA
$I_O$	output current	$-0.5\text{ V} < V_O < V_{CC} + 0.5\text{ V}$	-	$\pm 25$	mA
$I_{CC}$	supply current		-	50	mA
$I_{GND}$	ground current		-50	-	mA
$T_{stg}$	storage temperature		-65	+150	°C

**Table 3. Limiting values ...continued**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = -40 °C to +125 °C			
		SO16 package [2]	-	500	mW
		(T)SSOP16 package [3]	-	500	mW
		DHVQFN16 package [4]	-	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] P<sub>tot</sub> derates linearly with 8 mW/K above 70 °C.

[3] P<sub>tot</sub> derates linearly with 5.5 mW/K above 60 °C.

[4] P<sub>tot</sub> derates linearly with 4.5 mW/K above 60 °C.

## 9. Recommended operating conditions

**Table 4. Recommended operating conditions**

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	74HC4060			74HCT4060			Unit
			Min	Typ	Max	Min	Typ	Max	
V <sub>CC</sub>	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
V <sub>I</sub>	input voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
V <sub>O</sub>	output voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
T <sub>amb</sub>	ambient temperature		-40	-	+125	-40	-	+125	°C
Δt/ΔV	input transition rise and fall rate	V <sub>CC</sub> = 2.0 V	-	-	625	-	-	-	ns/V
		V <sub>CC</sub> = 4.5 V	-	1.67	139	-	1.67	139	ns/V
		V <sub>CC</sub> = 6.0 V	-	-	83	-	-	-	ns/V

## 10. Static characteristics

**Table 5. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HC4060</b>										
V <sub>IH</sub>	HIGH-level input voltage	MR input								
		V <sub>CC</sub> = 2.0 V	1.5	1.3	-	1.5	-	1.5	-	V
		V <sub>CC</sub> = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V <sub>CC</sub> = 6.0 V	4.2	3.1	-	4.2	-	4.2	-	V
		RS input								
		V <sub>CC</sub> = 2.0 V	1.7	-	-	1.7	-	1.7	-	V
		V <sub>CC</sub> = 4.5 V	3.6	-	-	3.6	-	3.6	-	V
V <sub>CC</sub> = 6.0 V	4.8	-	-	4.8	-	4.8	-	V		

**Table 5. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V <sub>IL</sub>	LOW-level input voltage	MR input								
		V <sub>CC</sub> = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V <sub>CC</sub> = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V <sub>CC</sub> = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
		RS input								
		V <sub>CC</sub> = 2.0 V	-	-	0.3	-	0.3	-	0.3	V
		V <sub>CC</sub> = 4.5 V	-	-	0.9	-	0.9	-	0.9	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>CC</sub> = 6.0 V	-	-	1.2	-	1.2	-	1.2	V
		RTC output; RS = MR = GND								
		I <sub>O</sub> = -20 µA; V <sub>CC</sub> = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I <sub>O</sub> = -20 µA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -20 µA; V <sub>CC</sub> = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I <sub>O</sub> = -2.6 mA; V <sub>CC</sub> = 4.5 V	3.98	-	-	3.84	-	3.7	-	V
		I <sub>O</sub> = -3.3 mA; V <sub>CC</sub> = 6.0 V	5.48	-	-	5.34	-	5.2	-	V
		RTC output; RS = MR = V <sub>CC</sub>								
		I <sub>O</sub> = -20 µA; V <sub>CC</sub> = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I <sub>O</sub> = -20 µA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -20 µA; V <sub>CC</sub> = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I <sub>O</sub> = -0.65 mA; V <sub>CC</sub> = 4.5 V	3.98	-	-	3.84	-	3.7	-	V
		I <sub>O</sub> = -0.85 mA; V <sub>CC</sub> = 6.0 V	5.48	-	-	5.34	-	5.2	-	V
		CTC output; RS = V <sub>IH</sub> ; MR = V <sub>IL</sub>								
		I <sub>O</sub> = -3.2 mA; V <sub>CC</sub> = 4.5 V	3.98	-	-	3.84	-	3.7	-	V
		I <sub>O</sub> = -4.2 mA; V <sub>CC</sub> = 6.0 V	5.48	-	-	5.34	-	5.2	-	V
		V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; except RTC output								
		I <sub>O</sub> = -20 µA; V <sub>CC</sub> = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I <sub>O</sub> = -20 µA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -20 µA; V <sub>CC</sub> = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; except RTC and CTC outputs										
I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 4.5 V	3.98	-	-	3.84	-	3.7	-	V		
I <sub>O</sub> = -5.2 mA; V <sub>CC</sub> = 6.0 V	5.48	-	-	5.34	-	5.2	-	V		

**Table 5. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V <sub>OL</sub>	LOW-level output voltage	RTC output; RS = V <sub>CC</sub> ; MR = GND								
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 2.6 mA; V <sub>CC</sub> = 4.5 V	-	-	0.26	-	0.33	-	0.4	V
		I <sub>O</sub> = 3.3 mA; V <sub>CC</sub> = 6.0 V	-	-	0.26	-	0.33	-	0.4	V
		CTC output; RS = V <sub>IL</sub> ; MR = V <sub>IH</sub>								
		I <sub>O</sub> = 3.2 mA; V <sub>CC</sub> = 4.5 V	-	-	0.26	-	0.33	-	0.4	V
		I <sub>O</sub> = 4.2 mA; V <sub>CC</sub> = 6.0 V	-	-	0.26	-	0.33	-	0.4	V
		V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; except RTC output								
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; except RTC and CTC outputs										
I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 4.5 V	-	-	0.26	-	0.33	-	0.4	V		
I <sub>O</sub> = 5.2 mA; V <sub>CC</sub> = 6.0 V	-	-	0.26	-	0.33	-	0.4	V		
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V	-	-	±0.1	-	±1.0	-	±1.0	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 6.0 V	-	-	8.0	-	80	-	160	μA
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF
<b>74HCT4060</b>										
V <sub>IH</sub>	HIGH-level input voltage	MR input; <a href="#">[1]</a> V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	-	-	2.0	-	2.0	-	V
		RS input; V <sub>CC</sub> = 4.5 V	3.6	-	-	3.6	-	3.6	-	V
V <sub>IL</sub>	LOW-level input voltage	MR input; <a href="#">[1]</a> V <sub>CC</sub> = 4.5 V to 5.5 V	-	-	0.8	-	0.8	-	0.8	V
		RS input; V <sub>CC</sub> = 4.5 V	-	-	0.9	-	0.9	-	0.9	V



**Table 5. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V <sub>OH</sub>	HIGH-level output voltage	RTC output; RS = MR = V <sub>CC</sub>								
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -0.65 mA; V <sub>CC</sub> = 4.5 V	3.98	-	-	3.84	-	3.7	-	V
		RTC output; RS = MR = GND								
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -2.6 mA; V <sub>CC</sub> = 4.5 V	3.98	-	-	3.84	-	3.7	-	V
		CTC output; RS = V <sub>IH</sub> ; MR = V <sub>IL</sub>								
		I <sub>O</sub> = -3.2 mA; V <sub>CC</sub> = 4.5 V	3.98	-	-	3.84	-	3.7	-	V
		V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; except RTC output								
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; except RTC and CTC outputs										
I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 4.5 V	3.98	-	-	3.84	-	3.7	-	V		
V <sub>OL</sub>	LOW-level output voltage	RTC output; RS = V <sub>CC</sub> ; MR = GND								
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 2.6 mA; V <sub>CC</sub> = 4.5 V	-	-	0.26	-	0.33	-	0.4	V
		CTC output; RS = V <sub>IL</sub> ; MR = V <sub>IH</sub>								
		I <sub>O</sub> = 3.2 mA; V <sub>CC</sub> = 4.5 V	-	-	0.26	-	0.33	-	0.4	V
		V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; except RTC output								
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; except RTC and CTC outputs								
I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 4.5 V	-	-	0.26	-	0.33	-	0.4	V		
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V	-	-	±0.1	-	±1.0	-	±1.0	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V; I <sub>O</sub> = 0 A	-	-	8.0	-	80	-	160	μA
ΔI <sub>CC</sub>	additional supply current	per input pin; V <sub>I</sub> = V <sub>CC</sub> - 2.1 V; other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 4.5 V to 5.5 V; I <sub>O</sub> = 0 A	-	40	144	-	180	-	196	μA
C <sub>I</sub>	input capacitance		-	3.5	-	-	-	-	-	pF

[1] For HCT4060, only input MR (pin 12) has TTL input switching levels.

## 11. Dynamic characteristics

**Table 6. Dynamic characteristics**

$GND = 0\text{ V}$ ;  $C_L = 50\text{ pF}$  unless otherwise specified; for test circuit see [Figure 11](#).

Symbol	Parameter	Conditions	25 °C			−40 °C to +85 °C		−40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HC4060</b>										
$t_{pd}$	propagation delay	RS to Q3; see <a href="#">Figure 8</a> <sup>[1]</sup>								
		$V_{CC} = 2.0\text{ V}$	-	99	300	-	375	-	450	ns
		$V_{CC} = 4.5\text{ V}$	-	36	60	-	75	-	90	ns
		$V_{CC} = 5.0\text{ V}$ ; $C_L = 15\text{ pF}$	-	31	-	-	-	-	-	ns
		$V_{CC} = 6.0\text{ V}$	-	29	51	-	64	-	77	ns
		Qn to Qn+1; see <a href="#">Figure 9</a> <sup>[2]</sup>								
		$V_{CC} = 2.0\text{ V}$	-	22	80	-	100	-	120	ns
		$V_{CC} = 4.5\text{ V}$	-	8	16	-	20	-	24	ns
		$V_{CC} = 5.0\text{ V}$ ; $C_L = 15\text{ pF}$	-	6	-	-	-	-	-	ns
$V_{CC} = 6.0\text{ V}$	-	6	14	-	17	-	20	ns		
$t_{PHL}$	HIGH to LOW propagation delay	MR to Qn; see <a href="#">Figure 10</a>								
		$V_{CC} = 2.0\text{ V}$	-	55	175	-	220	-	265	ns
		$V_{CC} = 4.5\text{ V}$	-	20	35	-	44	-	53	ns
		$V_{CC} = 5.0\text{ V}$ ; $C_L = 15\text{ pF}$	-	17	-	-	-	-	-	ns
		$V_{CC} = 6.0\text{ V}$	-	16	30	-	37	-	45	ns
$t_t$	transition time	Qn; see <a href="#">Figure 8</a> <sup>[3]</sup>								
		$V_{CC} = 2.0\text{ V}$	-	19	75	-	95	-	110	ns
		$V_{CC} = 4.5\text{ V}$	-	7	15	-	19	-	22	ns
		$V_{CC} = 6.0\text{ V}$	-	6	13	-	16	-	19	ns
$t_w$	pulse width	RS (HIGH or LOW); see <a href="#">Figure 8</a>								
		$V_{CC} = 2.0\text{ V}$	80	17	-	100	-	120	-	ns
		$V_{CC} = 4.5\text{ V}$	16	6	-	20	-	24	-	ns
		$V_{CC} = 6.0\text{ V}$	14	5	-	17	-	20	-	ns
		MR (HIGH); see <a href="#">Figure 10</a>								
		$V_{CC} = 2.0\text{ V}$	80	25	-	100	-	120	-	ns
		$V_{CC} = 4.5\text{ V}$	16	9	-	20	-	24	-	ns
		$V_{CC} = 6.0\text{ V}$	14	7	-	17	-	20	-	ns
$t_{rec}$	recovery time	MR to RS; see <a href="#">Figure 10</a>								
		$V_{CC} = 2.0\text{ V}$	100	28	-	125	-	150	-	ns
		$V_{CC} = 4.5\text{ V}$	20	10	-	25	-	30	-	ns
		$V_{CC} = 6.0\text{ V}$	17	8	-	21	-	26	-	ns

**Table 6. Dynamic characteristics ...continued**  
*GND = 0 V; C<sub>L</sub> = 50 pF unless otherwise specified; for test circuit see Figure 11.*

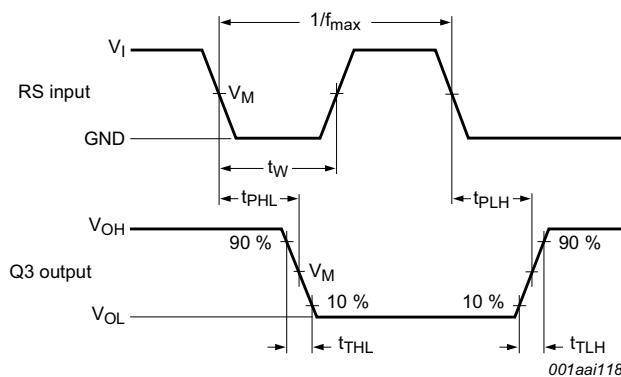
Symbol	Parameter	Conditions	25 °C			−40 °C to +85 °C		−40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
f <sub>max</sub>	maximum frequency	RS; see <a href="#">Figure 8</a>								
		V <sub>CC</sub> = 2.0 V	6	26	-	4.8	-	4	-	MHz
		V <sub>CC</sub> = 4.5 V	30	80	-	24	-	20	-	MHz
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	87	-	-	-	-	-	MHz
		V <sub>CC</sub> = 6.0 V	35	95	-	28	-	24	-	MHz
C <sub>PD</sub>	power dissipation capacitance	V <sub>I</sub> = GND to V <sub>CC</sub> ; V <sub>CC</sub> = 5 V; f <sub>i</sub> = 1 MHz <sup>[4]</sup>	-	40	-	-	-	-	-	pF
<b>74HCT4060</b>										
t <sub>pd</sub>	propagation delay	RS to Q3; see <a href="#">Figure 8</a> <sup>[1]</sup>								
		V <sub>CC</sub> = 4.5 V	-	33	66	-	83	-	99	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	31	-	-	-	-	-	ns
		Qn to Qn+1; see <a href="#">Figure 9</a> <sup>[2]</sup>								
		V <sub>CC</sub> = 4.5 V	-	8	16	-	20	-	24	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	6	-	-	-	-	ns	
t <sub>PHL</sub>	HIGH to LOW propagation delay	MR to Qn; see <a href="#">Figure 10</a>								
		V <sub>CC</sub> = 4.5 V	-	21	44	-	55	-	66	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	18	-	-	-	-	-	ns
t <sub>t</sub>	transition time	Qn; see <a href="#">Figure 8</a> <sup>[3]</sup>								
		V <sub>CC</sub> = 4.5 V	-	7	15	-	19	-	22	ns
t <sub>w</sub>	pulse width	RS (HIGH or LOW); see <a href="#">Figure 8</a>								
		V <sub>CC</sub> = 4.5 V	16	6	-	20	-	24	-	ns
		MR (HIGH); see <a href="#">Figure 10</a>								
		V <sub>CC</sub> = 4.5 V	16	6	-	20	-	24	-	ns
t <sub>rec</sub>	recovery time	MR to RS; see <a href="#">Figure 10</a>								
		V <sub>CC</sub> = 4.5 V	26	13	-	33	-	39	-	ns
f <sub>max</sub>	maximum frequency	RS; see <a href="#">Figure 8</a>								
		V <sub>CC</sub> = 4.5 V	30	80	-	24	-	20	-	MHz
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	-	88	-	-	-	-	-	MHz

**Table 6. Dynamic characteristics ...continued**  
*GND = 0 V; C<sub>L</sub> = 50 pF unless otherwise specified; for test circuit see Figure 11.*

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
C <sub>PD</sub>	power dissipation capacitance	V <sub>I</sub> = GND to V <sub>CC</sub> - 1.5 V; [4] V <sub>CC</sub> = 5 V; f <sub>i</sub> = 1 MHz	-	40	-	-	-	-	-	pF

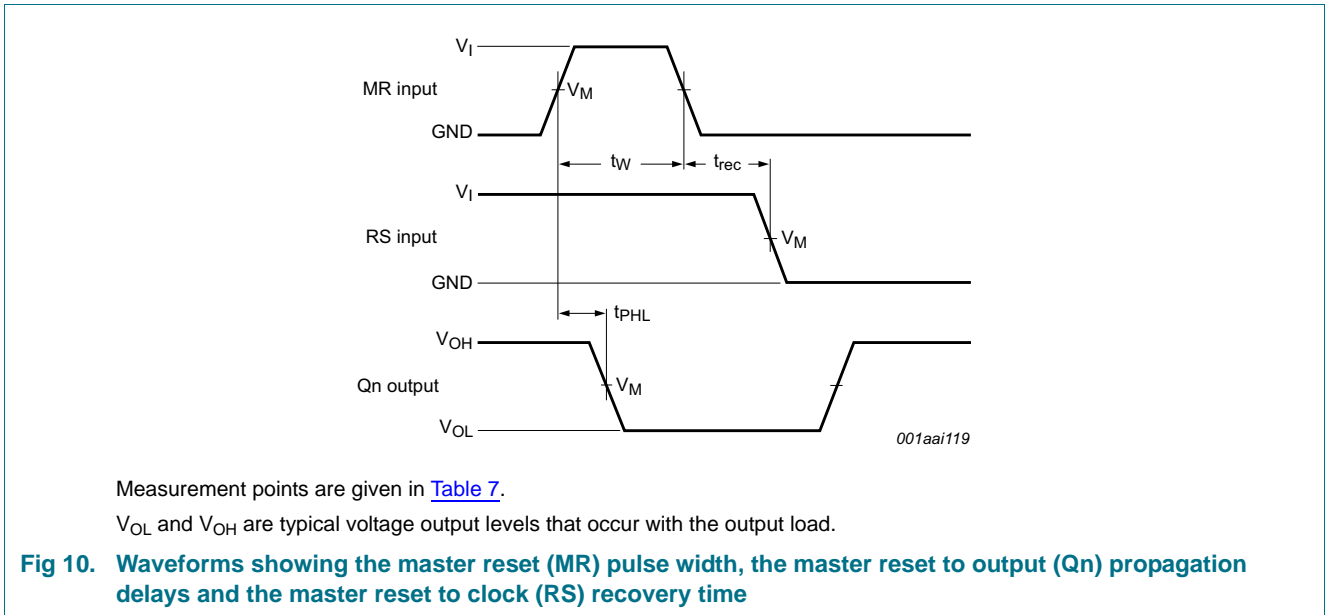
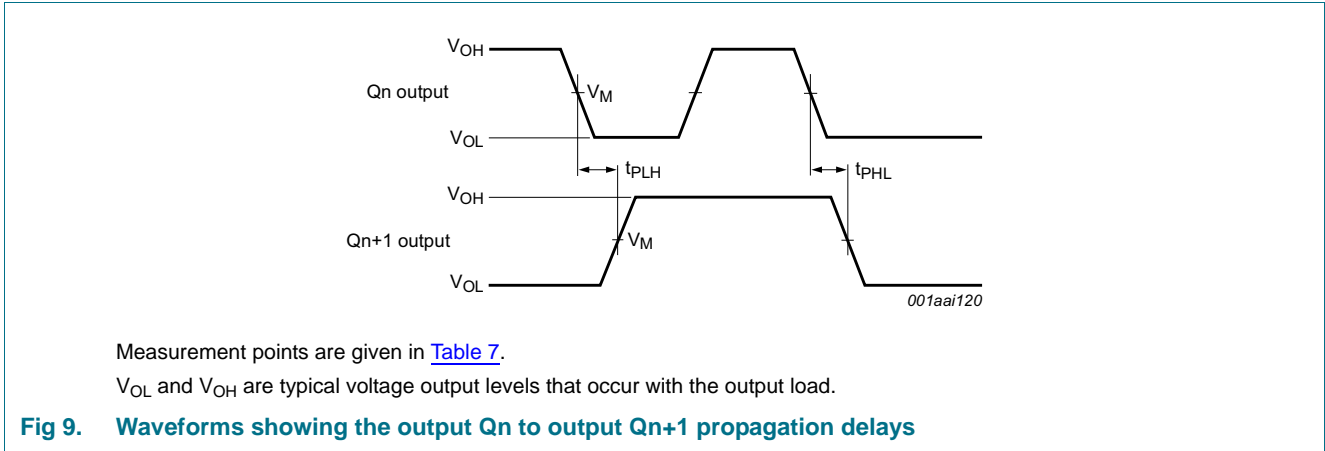
- [1] t<sub>pd</sub> is the same as t<sub>PHL</sub> and t<sub>PLH</sub>.
- [2] Q<sub>n+1</sub> is the next Q<sub>n</sub> output.
- [3] t<sub>i</sub> is the same as t<sub>THL</sub> and t<sub>TLH</sub>.
- [4] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW):  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o)$  where:  
 f<sub>i</sub> = input frequency in MHz;  
 f<sub>o</sub> = output frequency in MHz;  
 C<sub>L</sub> = output load capacitance in pF;  
 V<sub>CC</sub> = supply voltage in V;  
 N = number of inputs switching;  
 $\sum(C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.

## 12. Waveforms



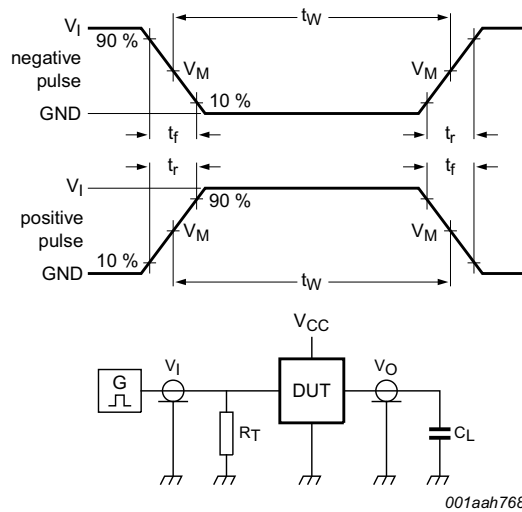
Measurement points are given in [Table 7](#).  
 V<sub>OL</sub> and V<sub>OH</sub> are typical voltage output levels that occur with the output load.

**Fig 8. Waveforms showing the clock (RS) to output (Q3) propagation delays, the clock pulse width, the output transition times and the maximum clock frequency**



**Table 7. Measurement points**

Type	Input	Output
	$V_M$	$V_M$
74HC4060	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
74HCT4060	1.3 V	1.3 V



Test data is given in [Table 8](#).

Definitions test circuit:

$R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

$C_L$  = Load capacitance including jig and probe capacitance.

**Fig 11. Test circuit for measuring switching times**

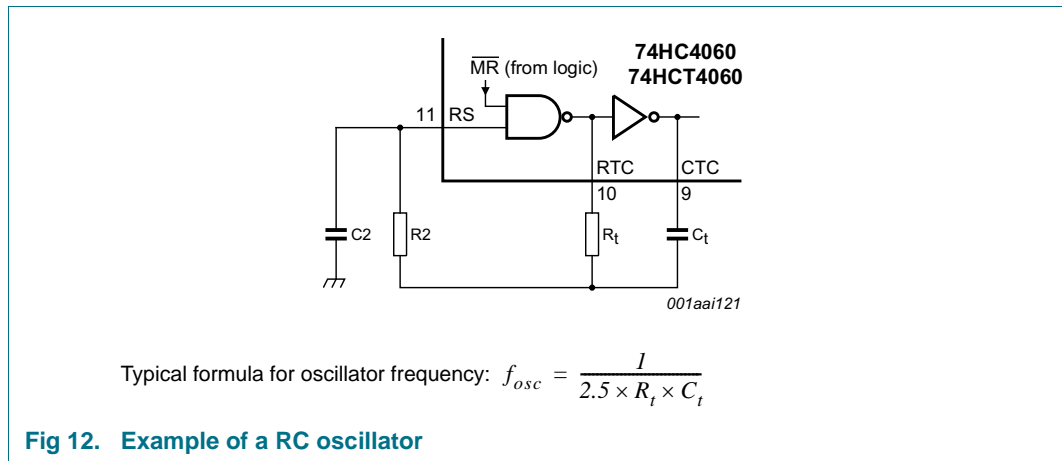
**Table 8. Test data**

Type	Input		Load
	$V_I$	$t_r, t_f$	$C_L$
74HC4060	$V_{CC}$	6 ns	15 pF, 50 pF
74HCT4060	3 V	6 ns	15 pF, 50 pF

## 13. RC oscillator

### 13.1 Timing component limitations

The oscillator frequency is mainly determined by  $R_t C_t$ , provided  $R_2 \approx 2R_t$  and  $R_2 C_2 \ll R_t C_t$ . The function of  $R_2$  is to minimize the influence of the forward voltage across the input protection diodes on the frequency. The stray capacitance  $C_2$  should be kept as small as possible. In consideration of accuracy,  $C_t$  must be larger than the inherent stray capacitance.  $R_t$  must be larger than the ON resistance in series with it, which typically is  $280 \Omega$  at  $V_{CC} = 2.0 \text{ V}$ ,  $130 \Omega$  at  $V_{CC} = 4.5 \text{ V}$  and  $100 \Omega$  at  $V_{CC} = 6.0 \text{ V}$ .



**Fig 12. Example of a RC oscillator**

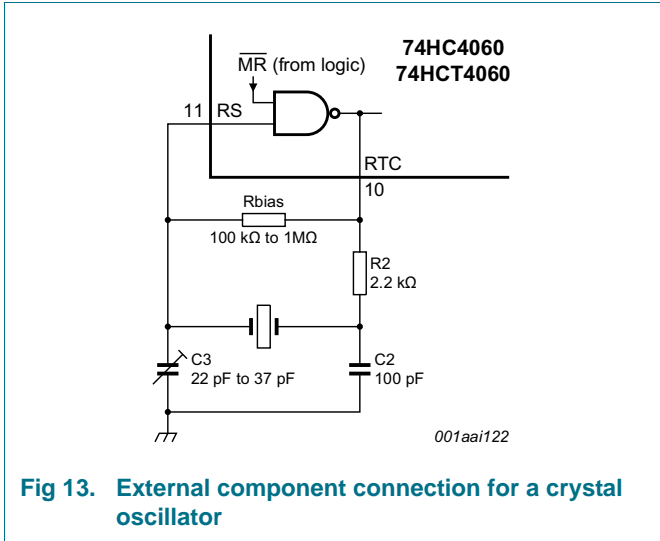
The recommended values for these components to maintain agreement with the typical oscillation formula are:

$C_t > 50 \text{ pF}$ , up to any practical value and  $10 \text{ k}\Omega < R_t < 1 \text{ M}\Omega$ .

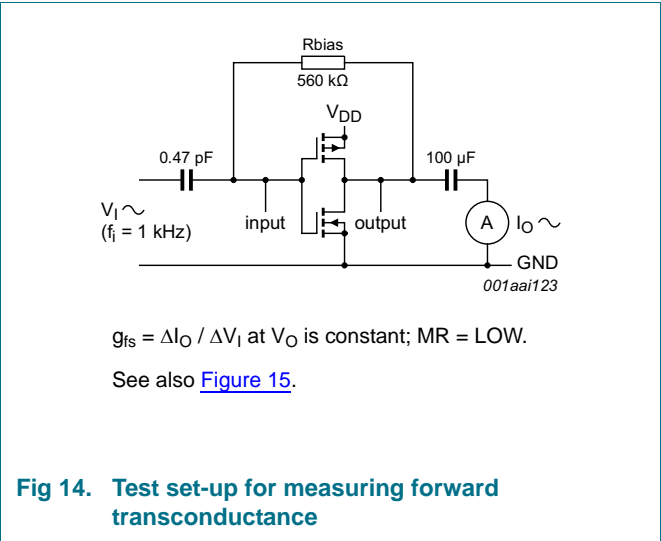
In order to avoid start-up problems,  $R_t \geq 1 \text{ k}\Omega$ .

### 13.2 Typical crystal oscillator circuit

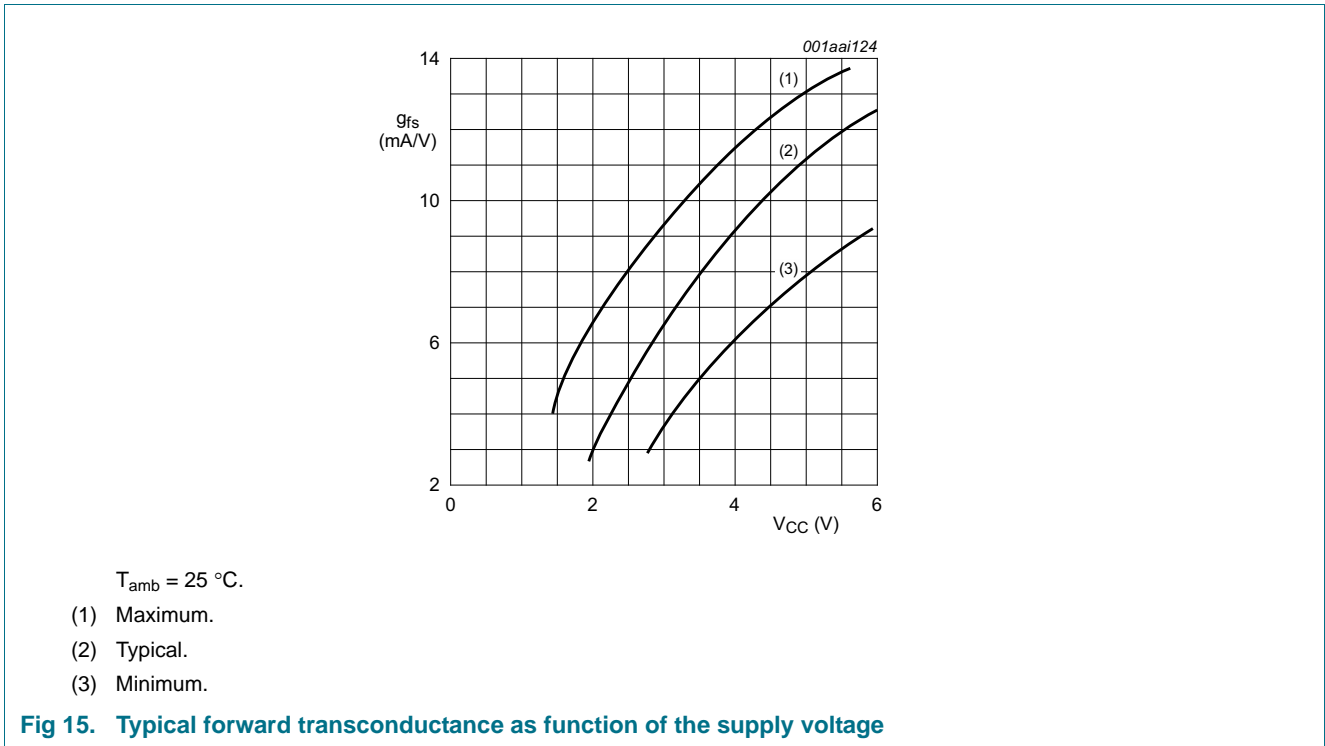
In [Figure 13](#),  $R_2$  is the power limiting resistor. For starting and maintaining oscillation a minimum transconductance is necessary, so  $R_2$  should not be too large. A practical value for  $R_2$  is  $2.2 \text{ k}\Omega$ .



**Fig 13. External component connection for a crystal oscillator**

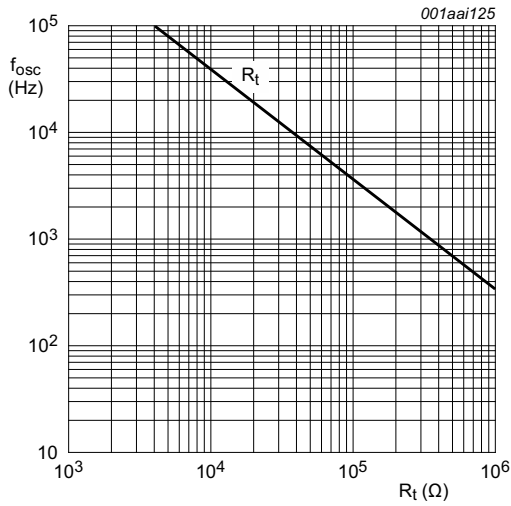


**Fig 14. Test set-up for measuring forward transconductance**



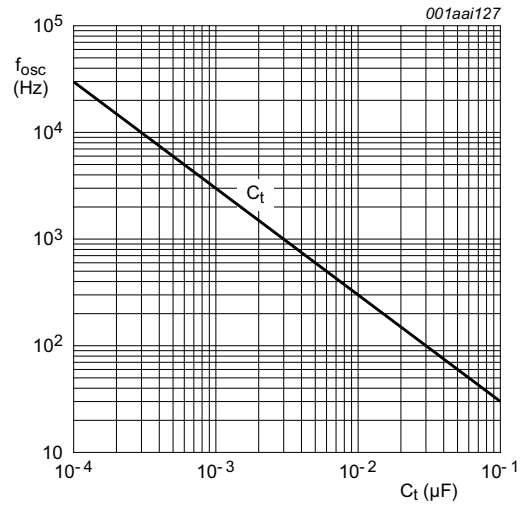
**Fig 15. Typical forward transconductance as function of the supply voltage**





$V_{CC} = 2.0\text{ V to }6.0\text{ V}; T_{amb} = 25\text{ }^{\circ}\text{C}.$   
 For  $R_t$  curve:  $C_t = 1\text{ nF}; R_2 = 2 \times R_t.$

**Fig 16. RC oscillator frequency as a function of  $R_t$**



$V_{CC} = 2.0\text{ V to }6.0\text{ V}; T_{amb} = 25\text{ }^{\circ}\text{C}.$   
 For  $C_t$  curve:  $R_t = 100\text{ k}\Omega; R_2 = 200\text{ k}\Omega.$

**Fig 17. RC oscillator frequency as a function of  $C_t$**

14. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

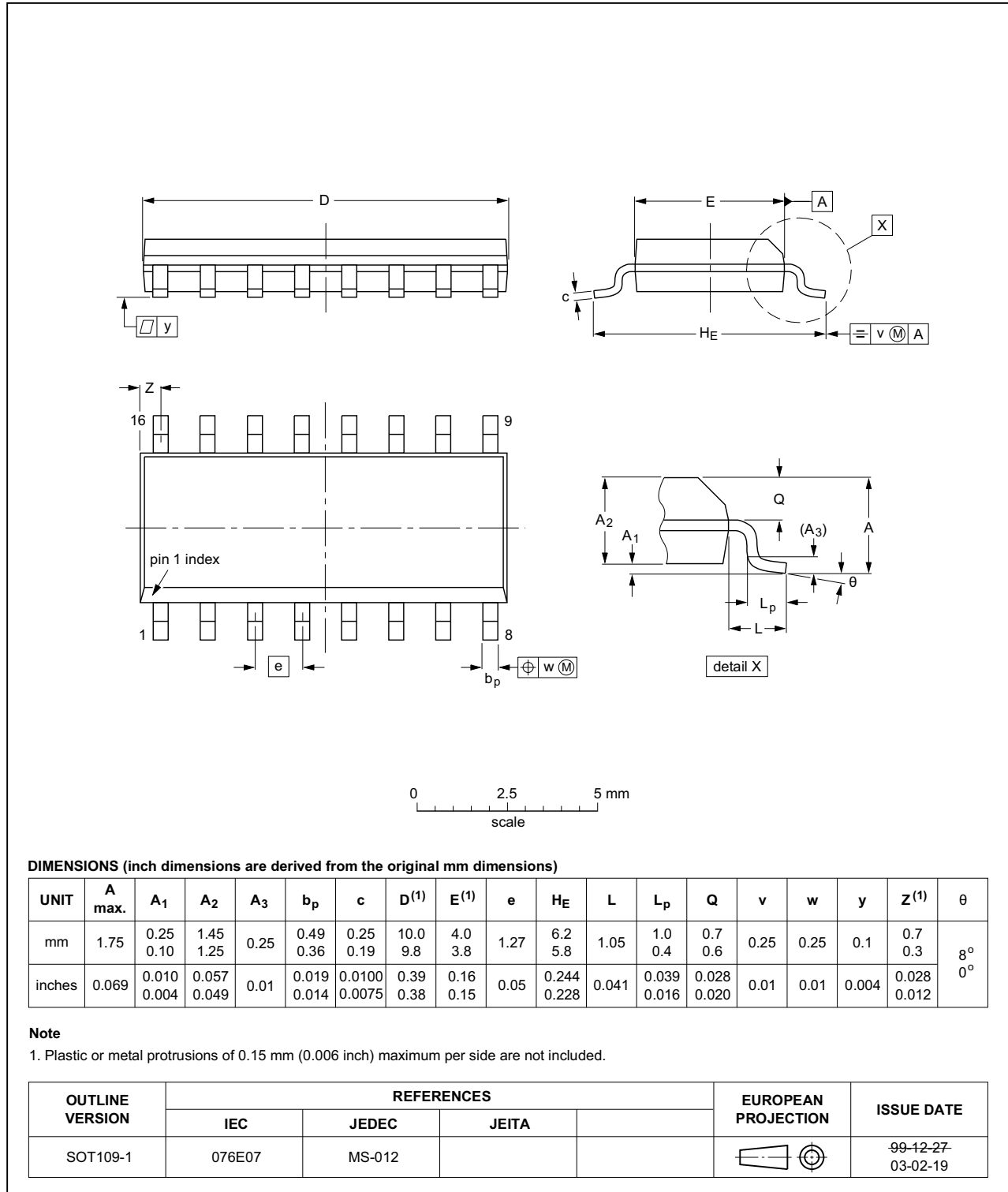


Fig 18. Package outline SOT109-1 (SO16)

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1

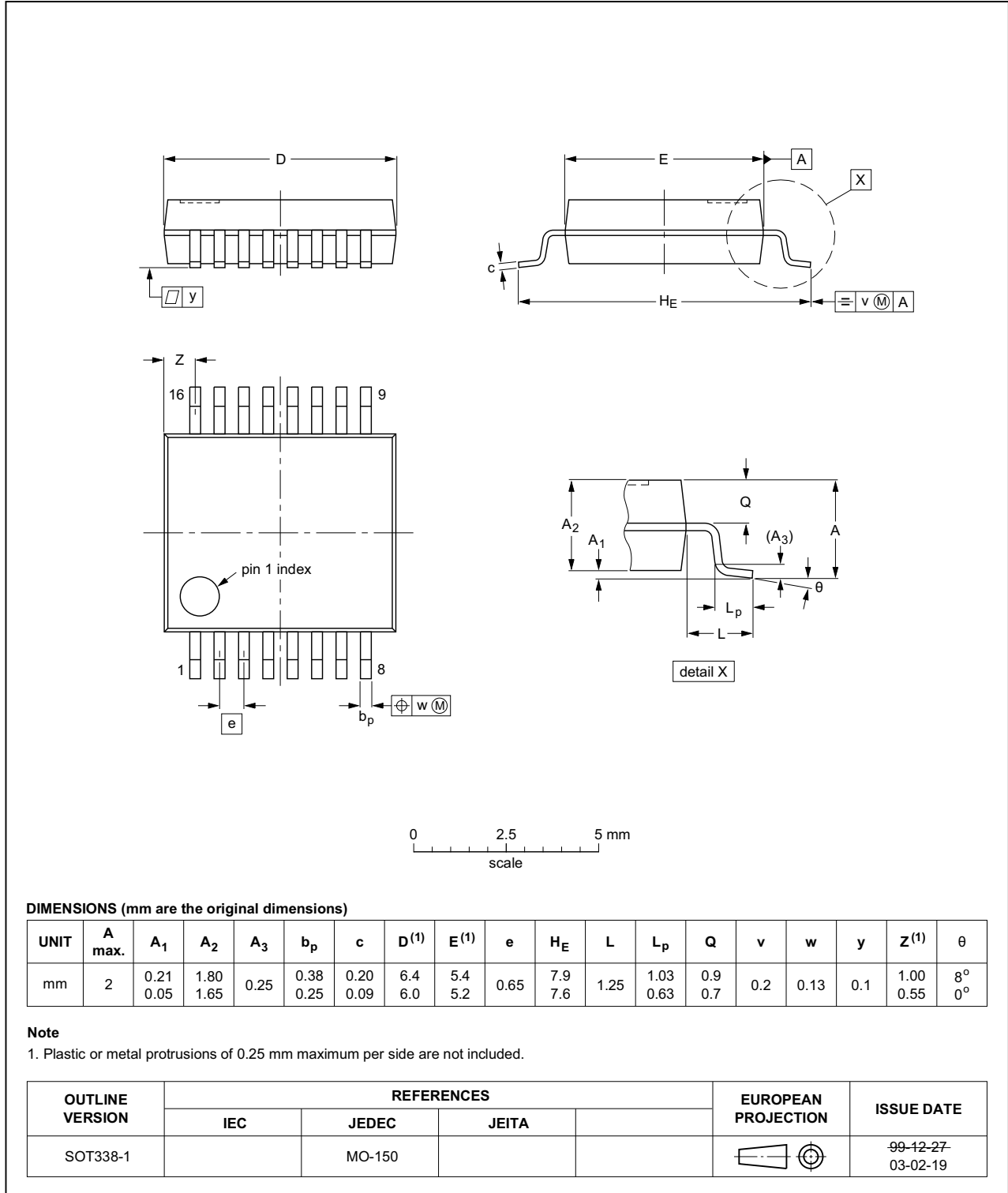


Fig 19. Package outline SOT338-1 (SSOP16)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1

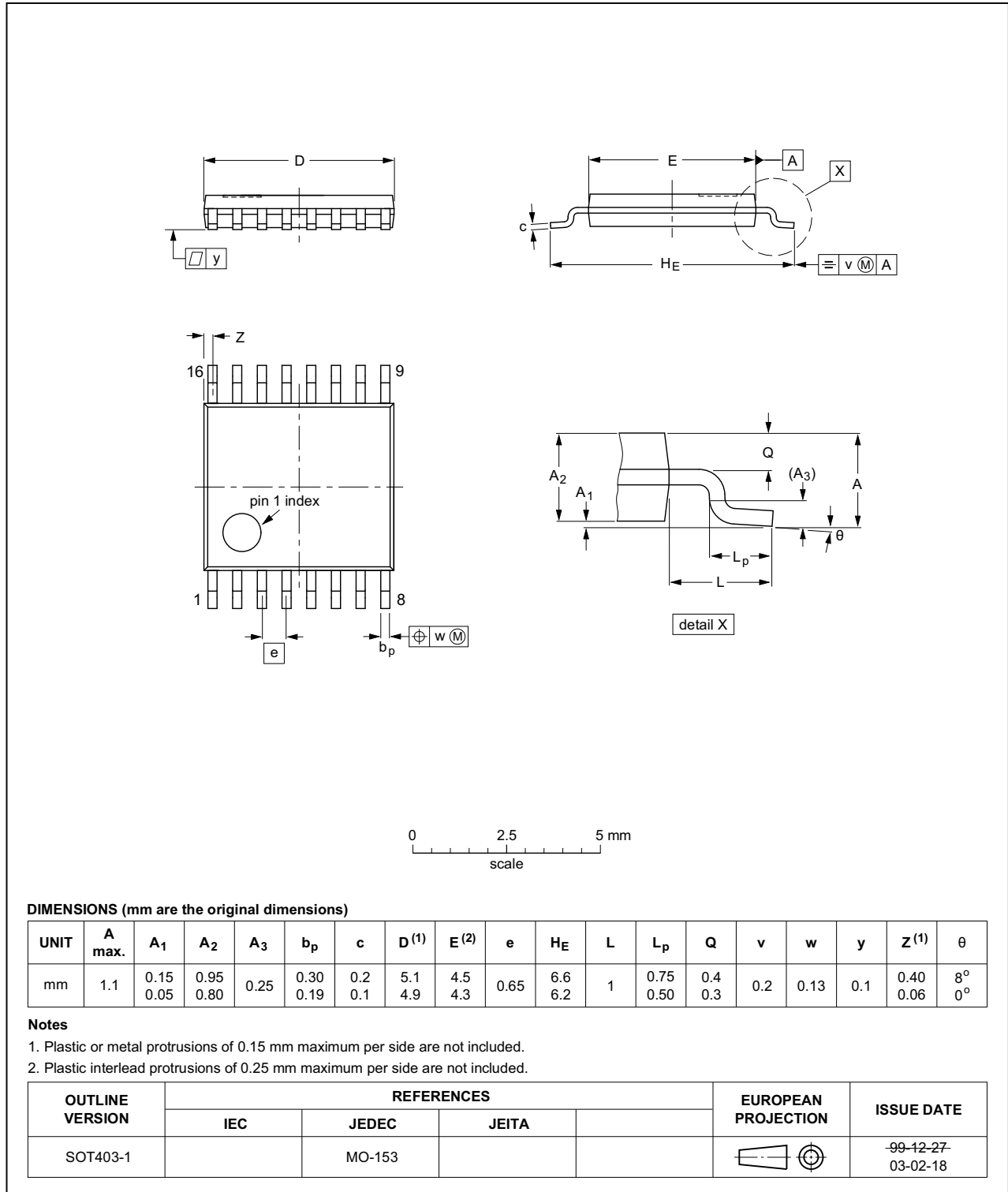
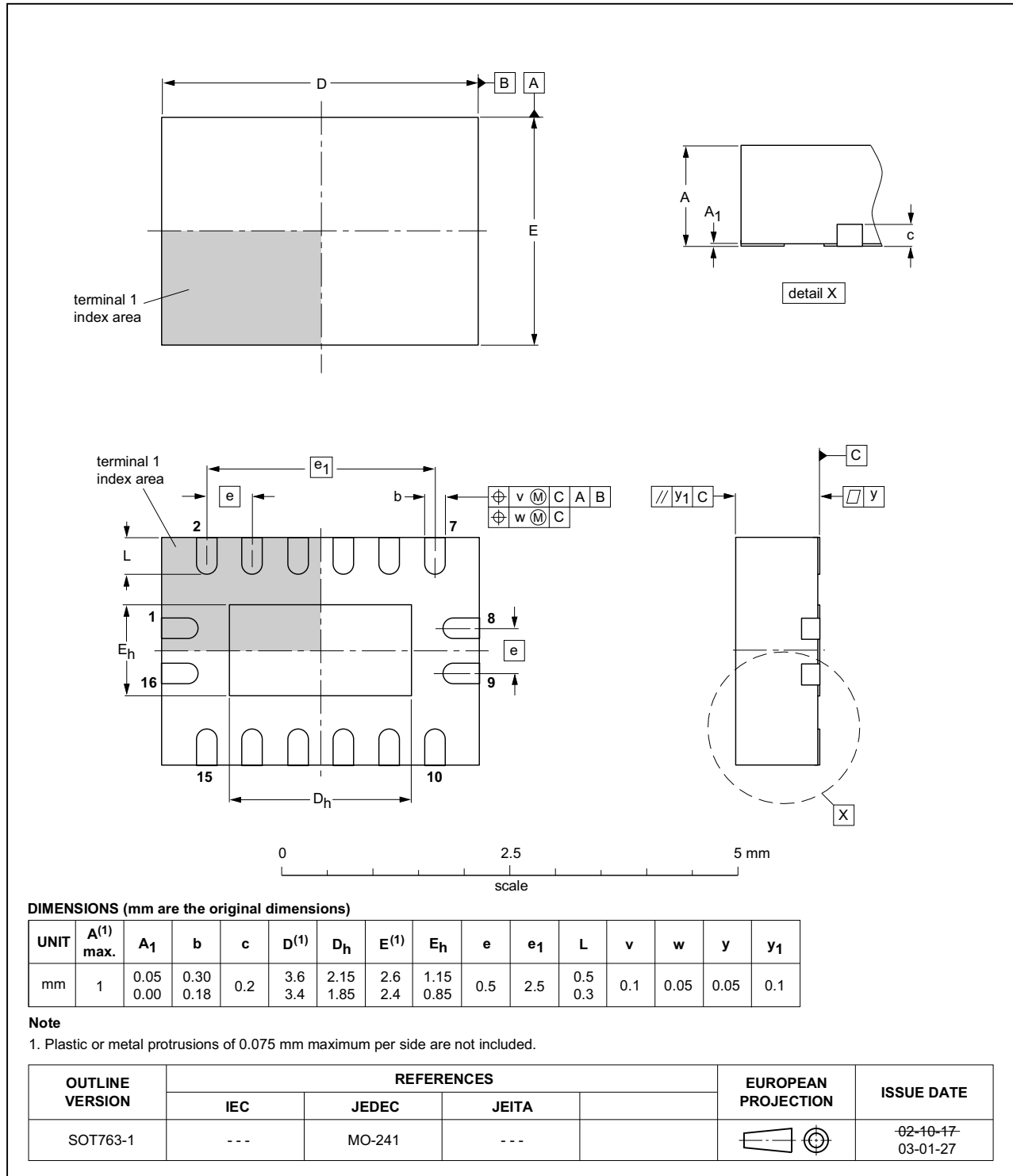


Fig 20. Package outline SOT403-1 (TSSOP16)

**DHVQFN16: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 x 3.5 x 0.85 mm**

**SOT763-1**



**Fig 21. Package outline SOT763-1 (DHVQFN16)**

## 15. Abbreviations

Table 9. Abbreviations

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

## 16. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT4060 v.4	20160210	Product data sheet	-	74HC_HCT4060 v.3
Modifications:	<ul style="list-style-type: none"> <li>Type numbers 74HC4060N and 74HCT4060N (SOT38-4) removed.</li> <li><a href="#">Table 5</a>: HIGH and LOW input levels added for 74HCT4060. (errata)</li> </ul>			
74HC_HCT4060 v.3	20080714	Product data sheet	-	74HC_HCT4060_CNV v.2
Modifications:	<ul style="list-style-type: none"> <li>The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li> <li>Legal texts have been adapted to the new company name where appropriate.</li> <li><a href="#">Section 4</a>: DHVQFN16 package added.</li> <li><a href="#">Section 8</a>: derating values added for DHVQFN16 package.</li> <li><a href="#">Section 14</a>: outline drawing added for DHVQFN16 package.</li> </ul>			
74HC_HCT4060_CNV v.2	19970901	Product specification	-	-

## 17. Legal information

### 17.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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